



DATE: 11th Jan, 2016

PCN #: 2218

PCN Title: Additional Qualified BOM (Bill of Materials) on select devices
manufactured at JCET in the DIP-7 package

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2218 REV 00

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
11 th Jan, 2016	10 th April, 2016	Analog Semiconductors	Additional BOM	2218
TITLE				
Additional Qualified BOM (Bill of Materials) on selected devices manufactured at JCET in the DIP-7 package				
DESCRIPTION OF CHANGE				
This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes has qualified additional BOM (Bill of Materials) on selected devices manufactured at JCET (Jiangsu Changjiang Electronics Technology Co., Ltd) in Suqian, China for the DIP-7 package. Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure there is no change to device functionality or electrical specifications in the datasheet.				
IMPACT				
Continuity of Supply. No change in datasheet parameters and product performance.				
PRODUCTS AFFECTED				
Please see the attached part list below in Table 1 which include the following changes: - Qualification of additional mold compound EMG-350 - Qualification of additional bonding wire material (Cu Wire) - Qualification of additional lead frame design with improved mold lock				
WEB LINKS				
Manufacturer's Notice:	http://www.diodes.com/quality/pcns			
For More Information Contact:	http://www.diodes.com/contacts			
Data Sheet:	http://www.diodes.com/products			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

Table 1 - Qualify Additional BOM (EMG-350 mold compound, Cu bond wire, and new mold lock lead frame design)					
AP3966P7-G1	AP3969P7-G1	AP3970P7-G1	AP3970P7-AG1	AP3970SP7-G1	AP3971P7-G1